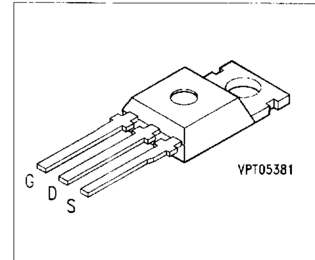
SIEMENS

SIPMOS® Power Transistor

BUZ 31

- N channel
- Enhancement mode
- Avalanche-rated



Type	V_{DS}	I_D	$R_{DS(on)}$	Package [1]	Ordering Code
BUZ 31	200 V	13.5 A	0.2 Ω	TO-220 AB	C67078-S1304-A2

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current, T_C = 28 °C	I_D	**13.5**	A
Pulsed drain current, T_C = 25 °C	$I_{D\,puls}$	**54**	
Avalanche current, limited by $T_{j\,max}$	I_{AR}	**13.5**	
Avalanche energy, periodic limited by $T_{j\,(max)}$	E_{AR}	**9**	mJ
Avalanche energy, single pulse I_D = 13.5 A, V_{DD} = 50 V, R_{GS} = 25 Ω L = 1.65 mH, T_j = 25 °C	E_{AS}	**200**	
Gate-source voltage	V_{GS}	**± 20**	V
Power dissipation, T_C = 25 °C	P_{tot}	**75**	W
Operating and storage temperature range	T_j , T_{stg}	**– 55 ... + 150**	°C

Thermal resistance, chip-case	$R_{th\,JC}$	**≤ 1.67**	K/W
DIN humidity category, DIN 40 040		**E**	–
IEC climatic category, DIN IEC 68-1		**55/150/56**	

1) See chapter Package Outlines.

Electrical Characteristics

at T_j = 25 °C, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static characteristics					
Drain-source breakdown voltage V_{GS} = 0 V, I_D = 0.25 mA	$V_{(BR)DSS}$	200	–	–	V
Gate threshold voltage $V_{GS} = V_{DS}$, I_D = 1 mA	$V_{GS(th)}$	2.1	3.0	4.0	
Zero gate voltage drain current V_{DS} = 200 V, V_{GS} = 0 V	I_{DSS}				µA
T_j = 25 °C		–	0.1	1.0	
T_j = 125 °C		–	10	100	
Gate-source leakage current V_{GS} = 20 V, V_{DS} = 0 V	I_{GSS}	–	10	100	nA
Drain-source on-resistance V_{GS} = 10 V, I_D = 8.5 A	$R_{DS(on)}$	–	0.16	0.2	Ω
Dynamic characteristics					
Forward transconductance $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$, I_D = 8.5 A	g_{fs}	5.0	10.0	–	S
Input capacitance V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	C_{iss}	–	960	1250	pF
Output capacitance V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	C_{oss}	–	200	330	
Reverse transfer capacitance V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	C_{rss}	–	100	170	
Turn-on time t_{on}, ($t_{on} = t_{d(on)} + t_r$) V_{DD} = 30 V, V_{GS} = 10 V, I_D = 3 A, R_{GS} = 50 Ω	$t_{d(on)}$	–	20	30	ns
	t_r	–	45	70	
Turn-off time t_{off}, ($t_{off} = t_{d(off)} + t_f$) V_{DD} = 30 V, V_{GS} = 10 V, I_D = 3 A, R_{GS} = 50 Ω	$t_{d(off)}$	–	180	230	
	t_f	–	60	80	

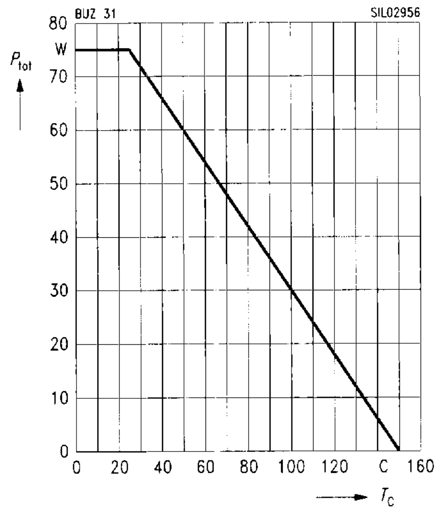
Electrical Characteristics (cont'd)
at T_j = 25 °C, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse diode					
Continuous reverse drain current T_C = 25 °C	I_S	–	–	13.5	A
Pulsed reverse drain current T_C = 25 °C	I_{SM}	–	–	54	
Diode forward on-voltage I_S = 27 A, V_{GS} = 0 V	V_{SD}	–	1.1	1.6	V
Reverse recovery time V_R = 100 V, $I_F = I_S$, di_F / dt = 100 A/µs	t_{rr}	–	180	–	ns
Reverse recovery charge V_R = 100 V, $I_F = I_S$, di_F / dt = 100 A/µs	Q_{rr}	–	1.2	–	µC

Characteristics at T_j = 25 °C, unless otherwise specified.

Total power dissipation

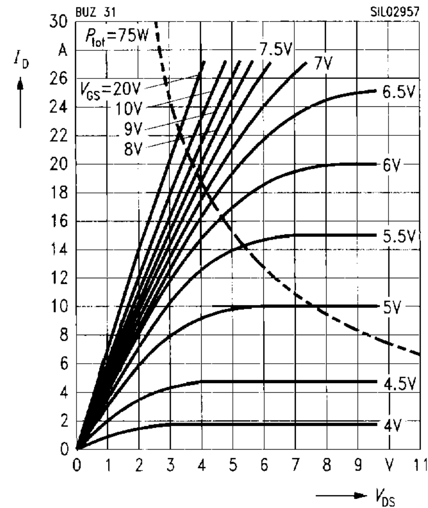
$P_{tot} = f(T_C)$



Typ. output characteristics

$I_D = f(V_{DS})$

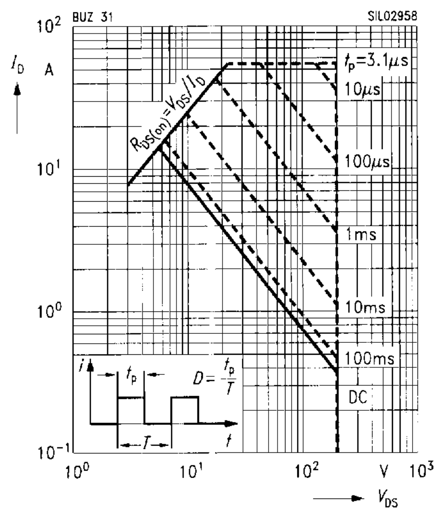
parameter: t_p = 80 µs



Safe operating area

$I_D = f(V_{DS})$

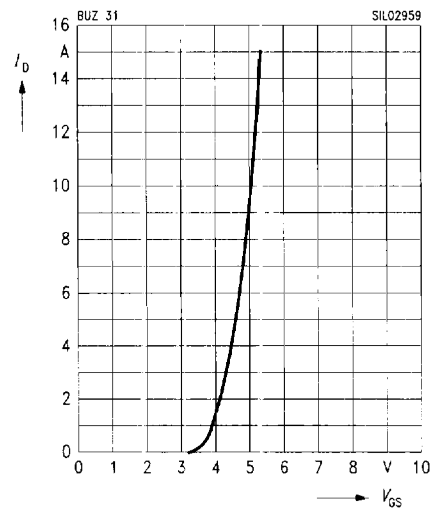
parameter: D = 0.01, T_C = 25 °C



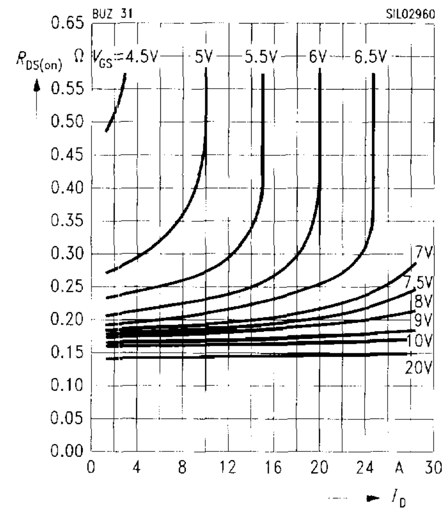
Typ. transfer characteristics

$I_D = f(V_{GS})$

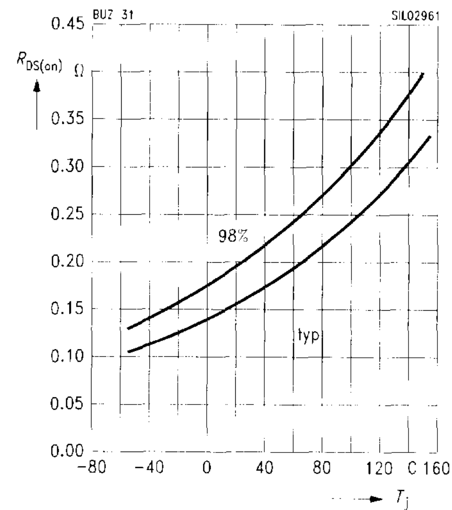
parameter: t_p = 80 µs, V_{DS} = 25 V



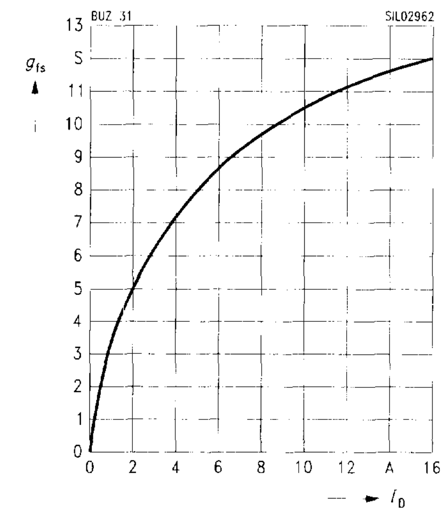
Typ. drain-source on-resistance
$R_{DS\,(on)} = f\,(I_D)$
parameter: V_{GS}



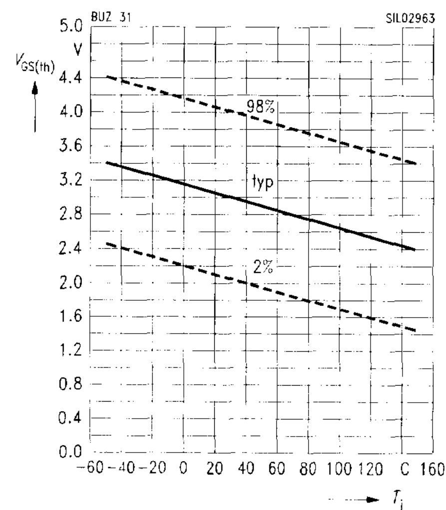
Drain-source on-resistance
$R_{DS\,(on)} = f\,(T_j)$
parameter: I_D = 8.5 A, V_{GS} = 10 V, (spread)



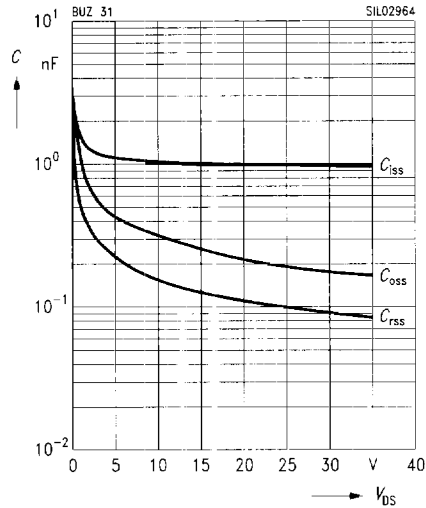
Typ. forward transconductance
$g_{fs} = f\,(I_D)$
parameter: t_p = 80 µs



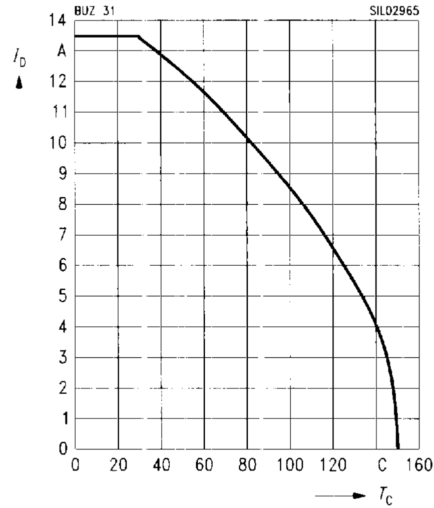
Gate threshold voltage
$V_{GS\,(th)} = f\,(T_j)$
parameter: $V_{GS} = V_{DS}$, I_D = 1 mA, (spread)



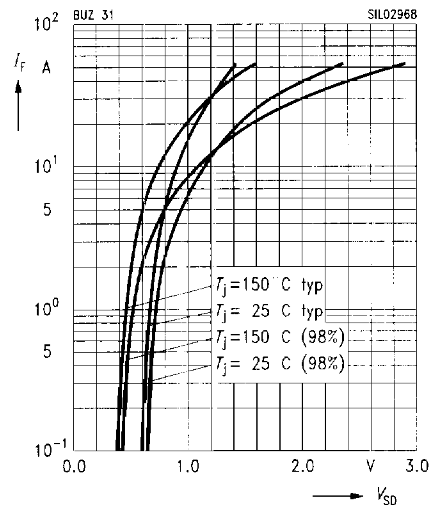
Typ. capacitances
$C = f(V_{DS})$
parameter: $V_{GS} = 0$ V, $f = 1$ MHz



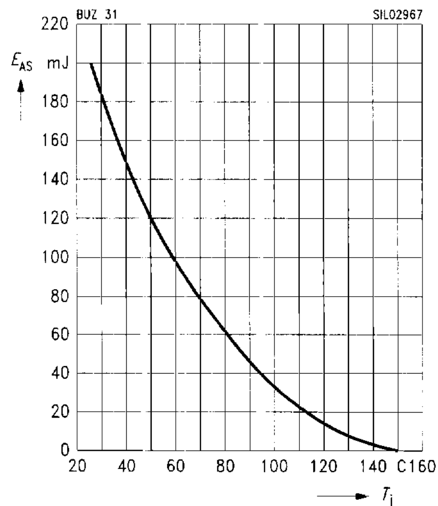
Drain current
$I_D = f(T_C)$
parameter: $V_{GS} \geq 10$ V



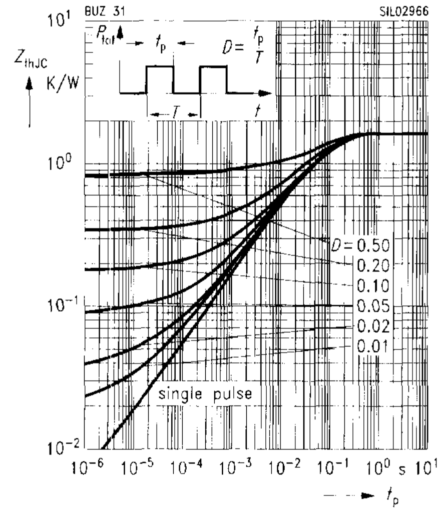
Forward characteristics of reverse diode
$I_F = f(V_{SD})$
parameter: T_j, $t_p = 80$ µs, (spread)



Avalanche energy $E_{AS} = f(T_j)$
parameter: $I_D = 13.5$ A, $V_{DD} = 50$ V
$R_{GS} = 25\ \Omega$, $L = 1.65$ mH



Transient thermal impedance
$Z_{th\,JC} = f(t_p)$
parameter: $D = t_p / T$



Typ. gate charge
$V_{GS} = f(Q_{Gate})$
parameter: $I_{D\,puls}$ = 20.3 A